



## Initial Product/Process Change Notification

Document #: IPCN23511XA

Issue Date: 16 Dec 2020

<b>Title of Change:</b>	SOT-23 5L Leadframe Design Change
<b>Proposed First Ship date:</b>	22 May 2021 or earlier if approved by customer
<b>Contact Information:</b>	Contact your local ON Semiconductor Sales Office or <a href="mailto:Joseph.Mendoza@onsemi.com">Joseph.Mendoza@onsemi.com</a>
<b>PCN Samples Contact:</b>	Contact your local ON Semiconductor Sales Office or <a href="mailto:PCN.samples@onsemi.com">&lt;PCN.samples@onsemi.com&gt;</a> . Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
<b>Type of Notification:</b>	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <a href="mailto:PCN.Support@onsemi.com">&lt;PCN.Support@onsemi.com&gt;</a>
<b>Marking of Parts/ Traceability of Change:</b>	Affected products will be identified with date code.
<b>Change Category:</b>	Assembly Change
<b>Change Sub-Category(s):</b>	Change in leadframe design

**Sites Affected:****ON Semiconductor Sites**



ON Semiconductor Cebu, Philippines

**External Foundry/Subcon Sites**

None

**Description and Purpose:**

Change in Die Attach pad (DAP) and leadpost dimensions to consolidate two similarly designed leadframes into one design.

	Before Change Description	After Change Description
LeadFrame	 <ul style="list-style-type: none"> <li>DAP Size: 1.321x1.092mm</li> <li>Leadpost Size: 0.445x0.203mm</li> </ul>	 <ul style="list-style-type: none"> <li>DAP Size: 1.676x1.219mm</li> <li>Leadpost Size: 0.295x0.203mm</li> </ul>

There is no product marking change as a result of this change.

**Qualification Plan:**QV DEVICE NAME: FIN1002M5XRMS: F69223, F69786PACKAGE: SOT-23 5L

Test	Specification	Condition	Interval
HTSL	JESD22-A103	Temp = 150°C	1,008 hrs
TC	JESD22-A104	Temp = -65°C to +150°C	1,000 cyc
HAST	JESD22-A110	Temp = 130°C, 85% RH, ~ 18.8 psig, bias = 100% of rated V or 100V max	96 hrs
UHAST	JESD22-A118	Temp = 130°C, RH=85%, ~18.8 psig, Unbiased	96 hrs
PC	J-STD-020, JESD22-A113	MSL 1 @ 260°C	-

Estimated date for qualification completion: 22 January 2021

**List of Affected Parts:**

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
FAN3111CSX-CBU	FIN1002M5X